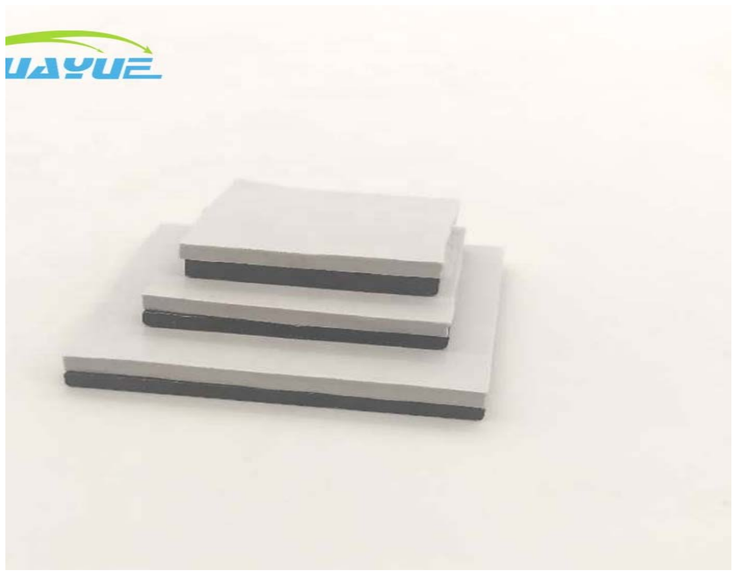
E硅胶导热垫

HC1000ESilicone thermal pad

TDS



HC1000E is a universal heat conducting gasket with no special heat dissipation requirements for hardness. Its softness can meet most of the pressure assembly requirements, showing a small thermal resistance, while eliminating the air between components and the circuit board, and fully filling various rough surfaces.The product comes with viscosity.The default is no base material structure, which can be customized to have a base material structure, such as back silicon tape /3M glue/glass fiber and other processes to meet special requirements.

Physical property parameters table		
Product performance	Test values	test method
Main components of materials	gray	—
color	Light purple	Visual
Thickness range (mm)	1.0 - 3.0	ASTM D374
Density (g/cc)	3.5	ASTM D792
Hardness (ShoreC)	30	ASTM D2240
Applicable temperature (℃)	-40 ~200	EN344
Insulation breakdown voltage (Vac)	>4000	ASTM D149
Dielectric constant (1MHz)	5.5	ASTM D150
Volume resistivity (Ohm-meter)	$8.3*10^{12}$	ASTM D257
Low molecular siloxane d3-d12 (PPM)	< 300	GB/T27843-2011
Fire rating	94V-0	U.L
Thermal conductivity (W/ m-k)	10.0	ASTM D5470
Recommended amount of compression	30%	—

The characteristics of

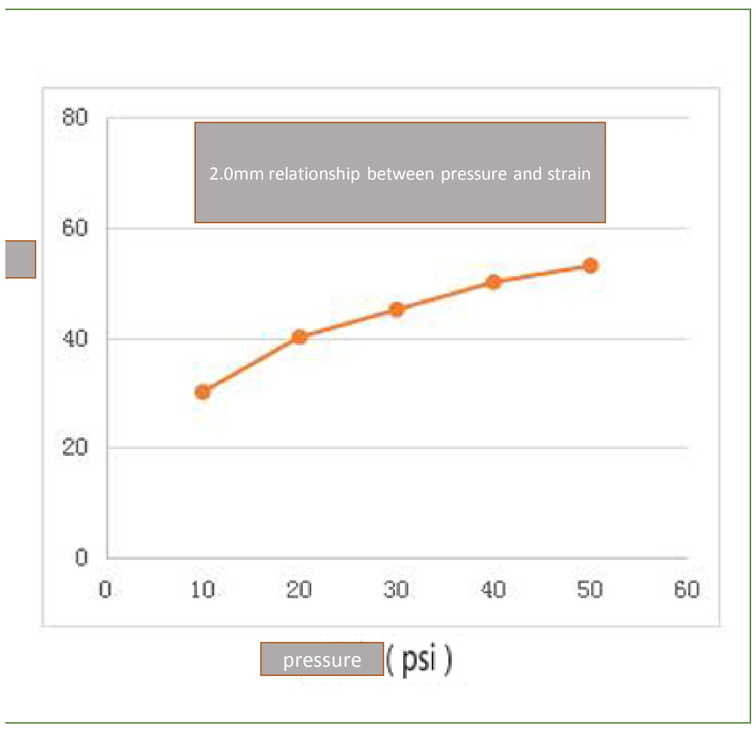
• thermal conductivity = 10.0w /m.k

• high adhesion, ultra-low hardness, suitable for low fastening pressure

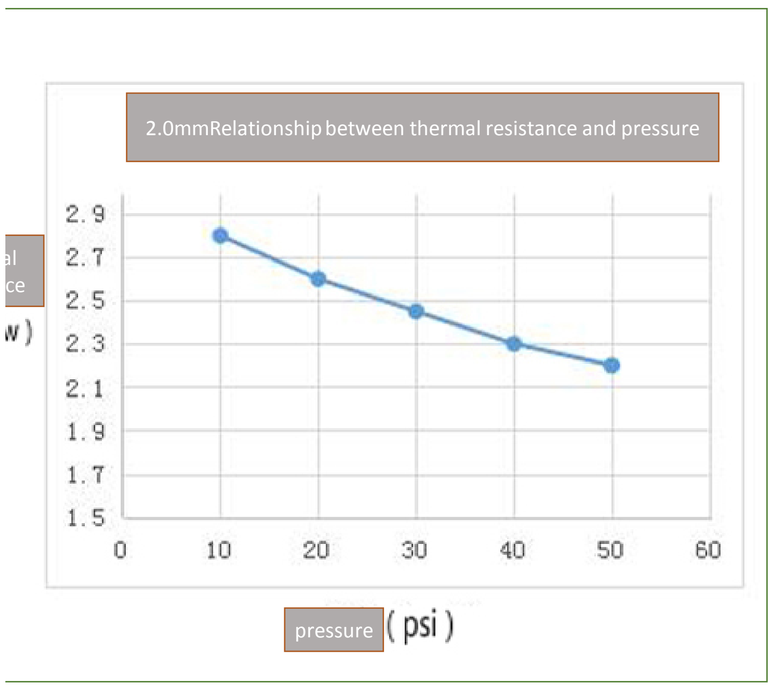
• fire protection meets V0 and environmental protection meets ROHS requirements

• good resilience

The relationship between stress and strain



The relationship between thickness and thermal resistance



Thickness tolerance ≤ 10% of product thickness

Typical applications

•Communications industry

•Computer and peripheral

•Power converter

•Between a semiconductor or magnetic body and a radiator

•Heat transfer frames, chassis or other heat transfer areas are required

Available specifications: sheet, die - cutting

Standard thickness mm: 0.3, 0.5, 1.0, 1.5, 2.0, 2.5, 3.0 other thickness needs to be customized

Standard length and width mm: 200*400, 300*400 other sizes need to be customized

Storage conditions: temperature 10-30℃, humidity: 70%

Description:

This product can be mixed with glass fiber (FG), single back silicon tape (SP), one side with viscosity and one side without viscosity (DC).Please refer to the MSDS report for the safety data of the product. The data in this paper are obtained under laboratory conditions. Due to the differences in the use conditions, users need to refer to these data and use conditions for analysis and test.The company does not guarantee the sale of the product or the use of the company's products under specific conditions, and is not liable for any direct, indirect or accidental loss.
If you have any problem, you can contact the technical service department of the company.

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